## **DSC7003**

## Silicon NPN epitaxial planar type

For low frequency output amplification Complementary to DSA7003 DSC8003 in MiniP3 type package

#### ■ Features

- $\bullet$  Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

### Packaging

DSC7003×0L Embossed type (Thermo-compression sealing): 1000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	50	V
Emitter-base voltage (Collector open)	V <sub>EBO</sub>	5	V
Collector current	$I_{C}$	1	A
Peak collector current	I <sub>CP</sub>	1.5	A
Collector power dissipation	P <sub>C</sub>	1	W
Junction temperature	T <sub>j</sub>	150	°C
Storage temperature	T <sub>stg</sub>	-55 to +150	°C

Note) Printed circuit board: Copper foil area of 1 cm<sup>2</sup> or more, and the board thickness of 1.7 mm for the collector portion

Absolute maximum rating without heat sink for P<sub>C</sub> is 0.5 W

### ■ Package

Code

MiniP3-F2-B

Package dimension clicks here.→

#### • Pin Name

- 1. Base
- 2. Collector
- 3. Emitter
- Marking Symbol: 5A

## ■ Electrical Characteristics $T_a = 25$ °C±3°C

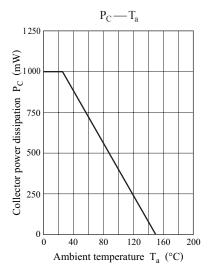
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	$I_C = 10 \mu A, I_E = 0$	60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μΑ
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}$	120		340	
	h <sub>FE2</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 1 \text{ A}$	50			
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.15	0.4	V
Base-emitter saturation voltage *1	V <sub>BE(sat)</sub>	$I_C = 500 \text{ mA}, I_B = 50 \text{ mA}$		0.9	1.2	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 50 \text{ mA}$		170		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		10	20	pF

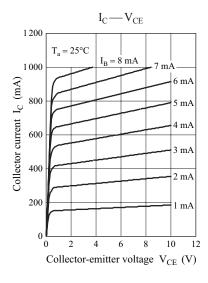
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

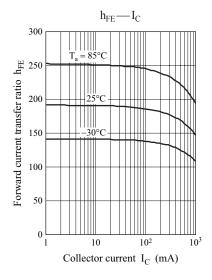
- 2. \*1: Pulse measurement
  - \*2: Rank classification

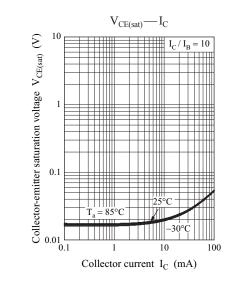
Code	R	S	0	
Rank	R	S	No-rank	
$h_{\mathrm{FE1}}$	120 to 240	170 to 340	120 to 340	
Marking Symbol	5AR	5AS	5A	

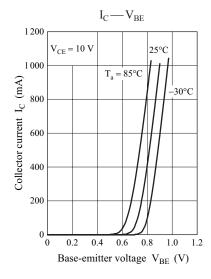
Product of no-rank is not classified and have no marking symbol for rank.

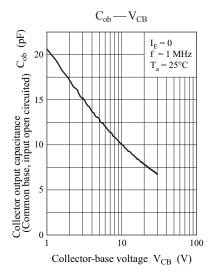


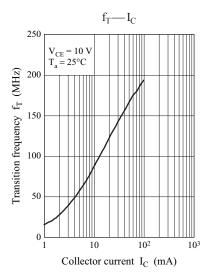












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